

# Timing Characterization of LGADs for Space Based Applications

A. Bisht, M. Boscardin, F. Caso, L. Cavazzini, M. Centis Vignali,  
F. Ficorella, O. Hammad Ali, G. Paternoster

[lcavazzini@fbk.eu](mailto:lcavazzini@fbk.eu)



UNIVERSITÀ  
DI TRENTO



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BRUNO KESSLER



PhD SST

Space Science  
and Technology

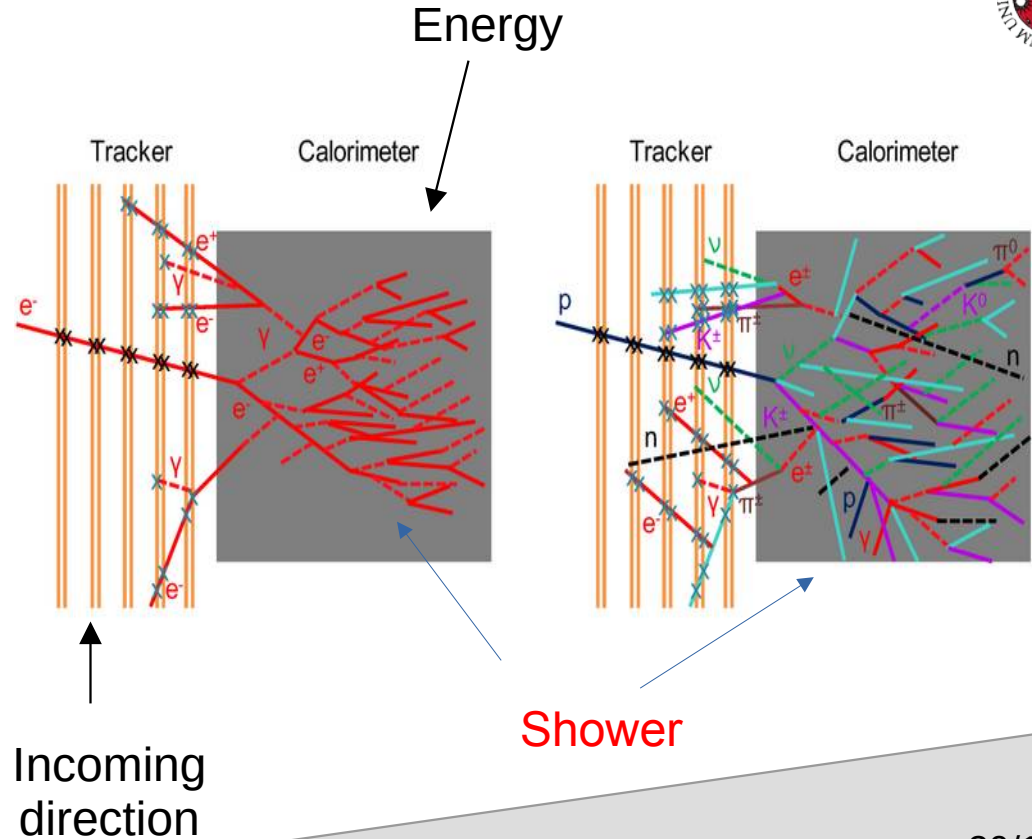
# The Scientific Reason

## Advantages of Timing

- Identification of back-scattered hits from calorimeters
- Time of Flight (ToF) measurements
- Improved e/p

## Requirements in Space

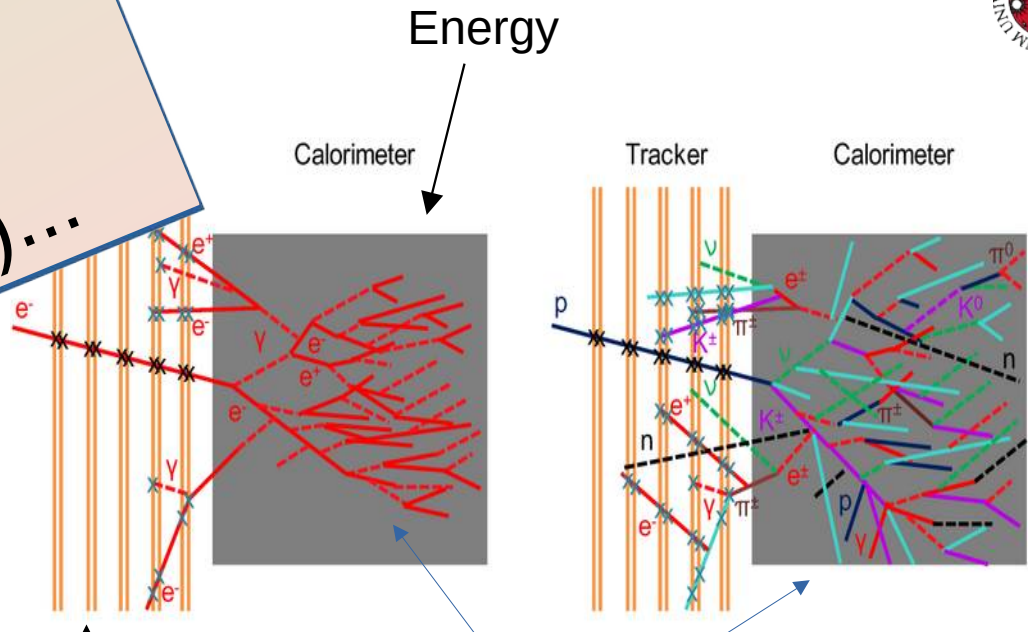
- Power consumption
- Timing  $O(100 \text{ ps})$
- Large Channel size  $\leftarrow$  (Small Particle Flux)



# The Scientific Reason

Advantages of LGADs are good candidates: Time resolution  $O(10 \text{ ps})$ ...

- Identification of hadrons in calorimeters
- Timing  $O(100 \text{ ps})$
- Large Channel
- Power consumption
- Timing  $O(100 \text{ ps})$
- Large Channel



But are produced with channels of few  $\text{mm}^2$

# Space LGAD production

## Active Thickness

- 50  $\mu\text{m}$
- 100  $\mu\text{m}$
- 150  $\mu\text{m}$

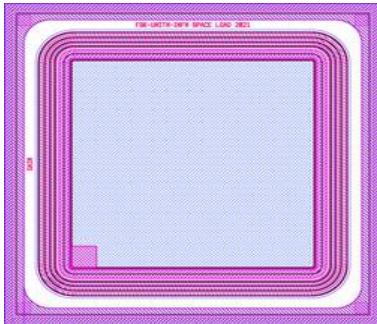
## Active Area

- 6.25  $\text{mm}^2$
- 25  $\text{mm}^2$
- 100  $\text{mm}^2$

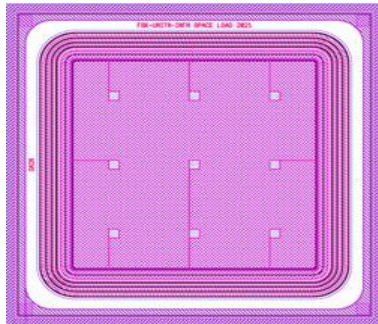
## Layout Types

- **Type 1:** Open Frame
- **Type 2:** Fully Metallized, Contacts at the edge of the active area
- **Type 3:** Fully Metallized, Contact points spread in the active area

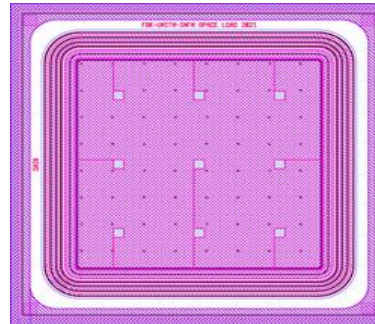
### Type 1



### Type 2



### Type 3





# Space LGAD production

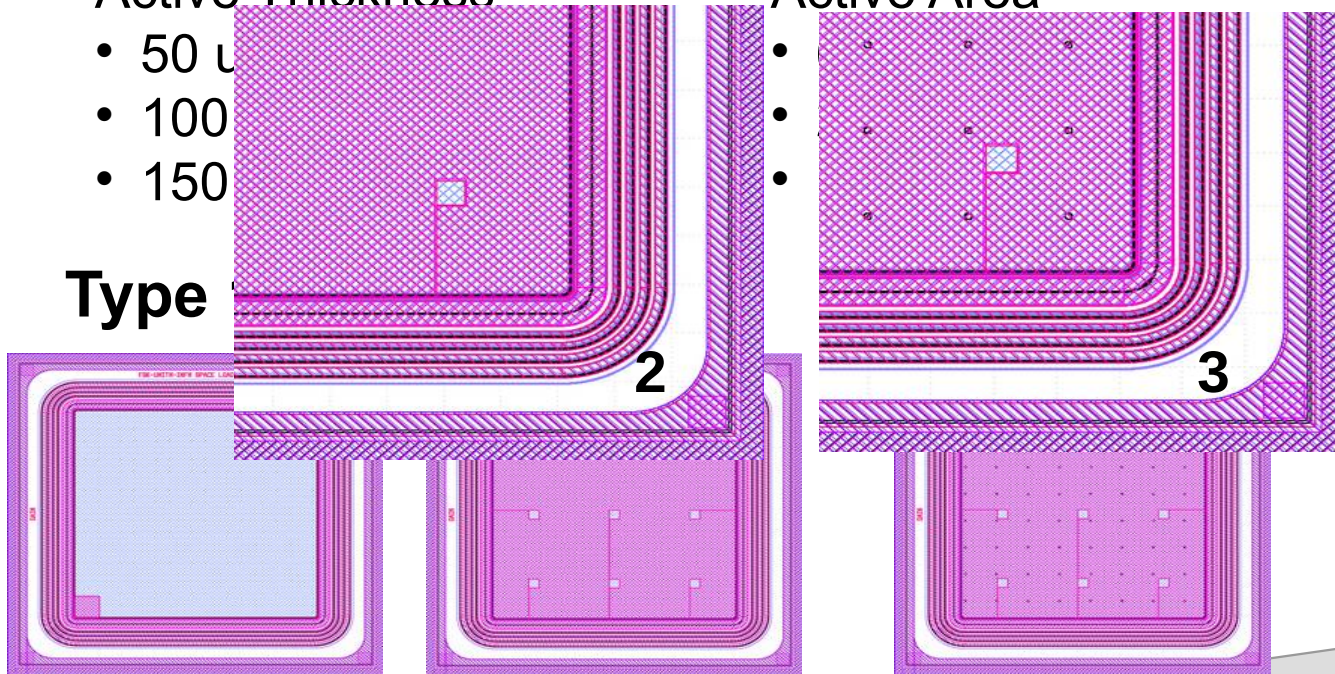
## Active Thickness

- 50  $\mu$ m
- 100  $\mu$ m
- 150  $\mu$ m

## Active Area

- 100  $\mu$ m
- 200  $\mu$ m
- 300  $\mu$ m

## Type

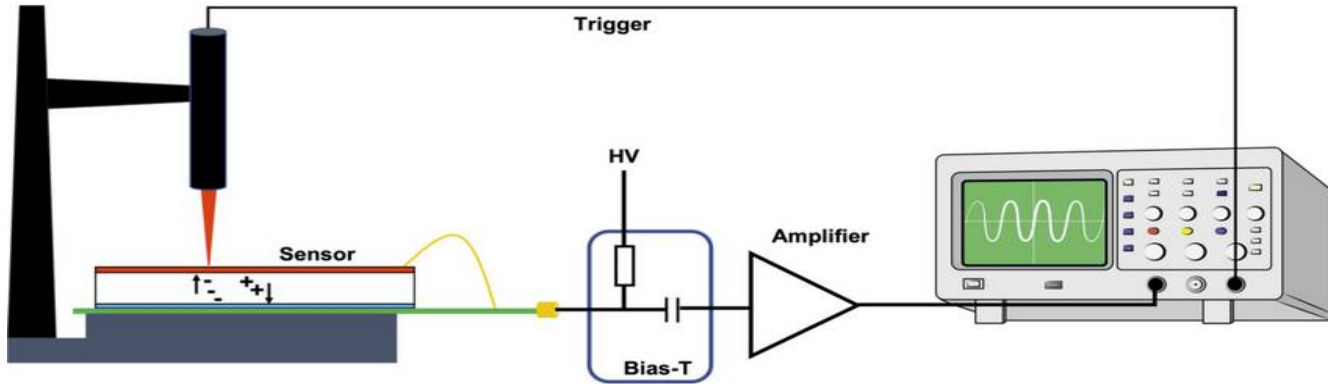


## Layout Types

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# The Setup

Setup: Scanning  
TCT, Particulars



[A. Bisht, Development of Low Gain  
Avalanche Detectors for Astroparticle  
Physics Experiments in Space, Trento 2023]

PCB: FNAL  
16 channels

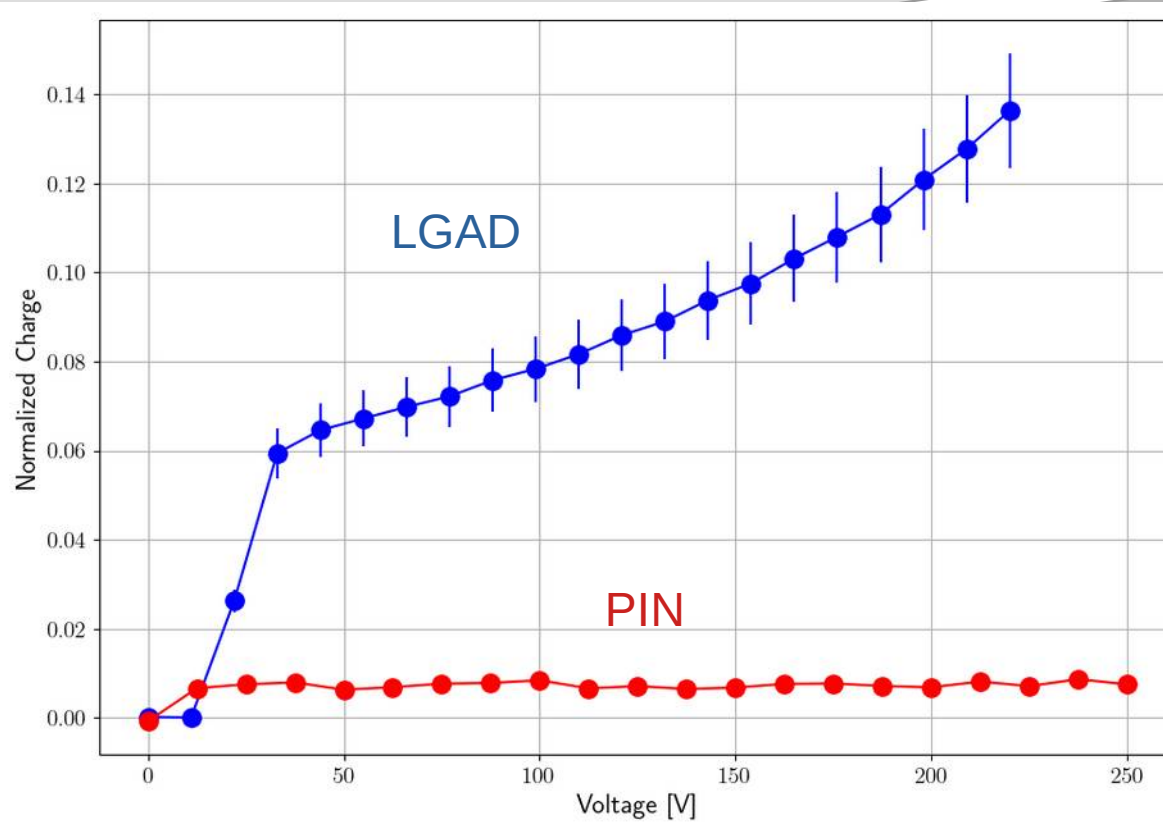
Infra-Red (1060 nm) and  
Red (600 nm) pulsed  
laser

X/Y translation stage (0.8  
um precision)

Beam Monitor

1 MIP calibration with  
radioactive source

# Gain

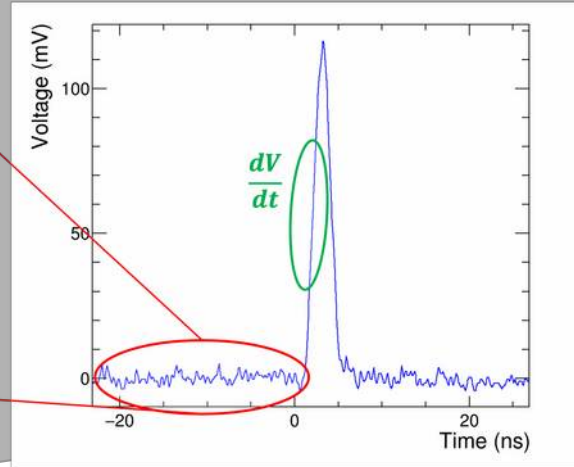
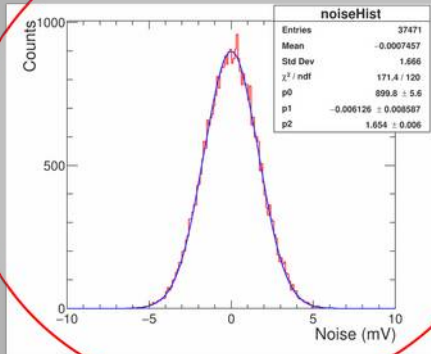
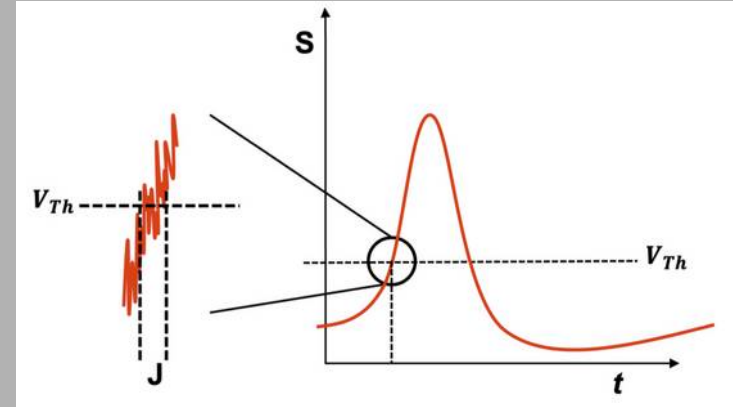


$$Gain = \frac{Ch_{LGAD}[fC]}{Ch_{PIN}[fC]}$$

# Jitter

Two Acquisitions:

- ✓ Single Waveform → Noise Estimation
- ✓ Average Waveform → Slew Rate Estimation via Fitting the leading edge



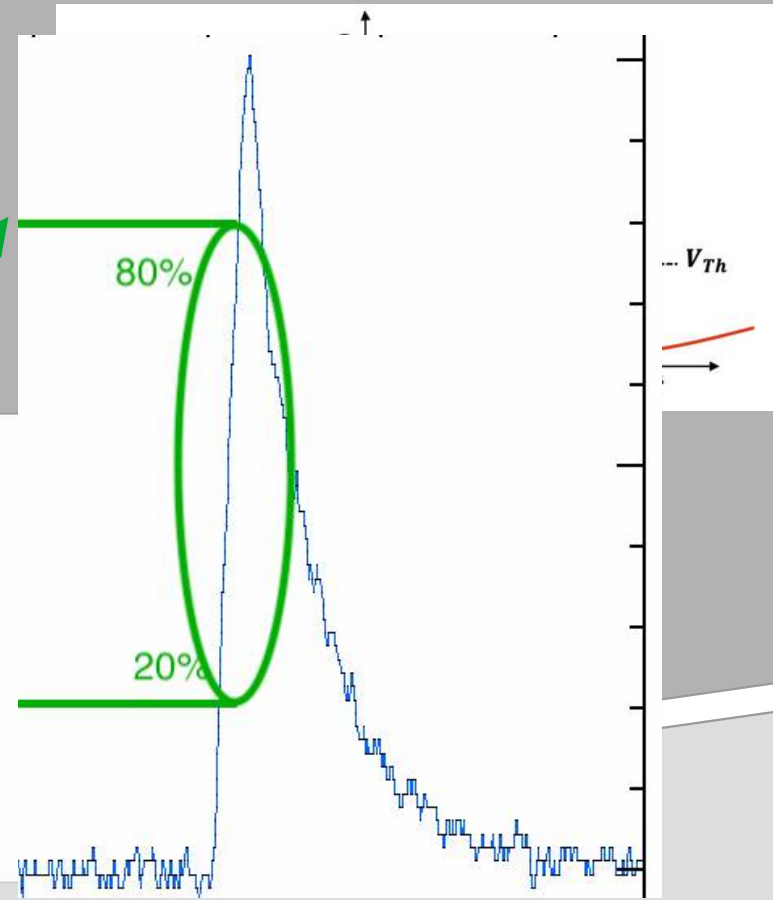
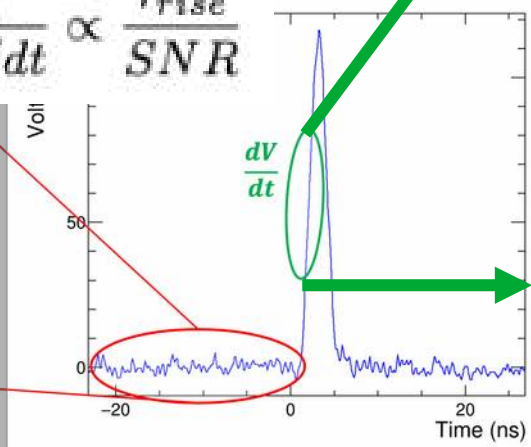
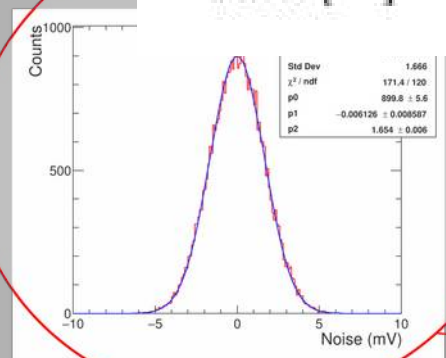


# Jitter

Two Acquisitions:

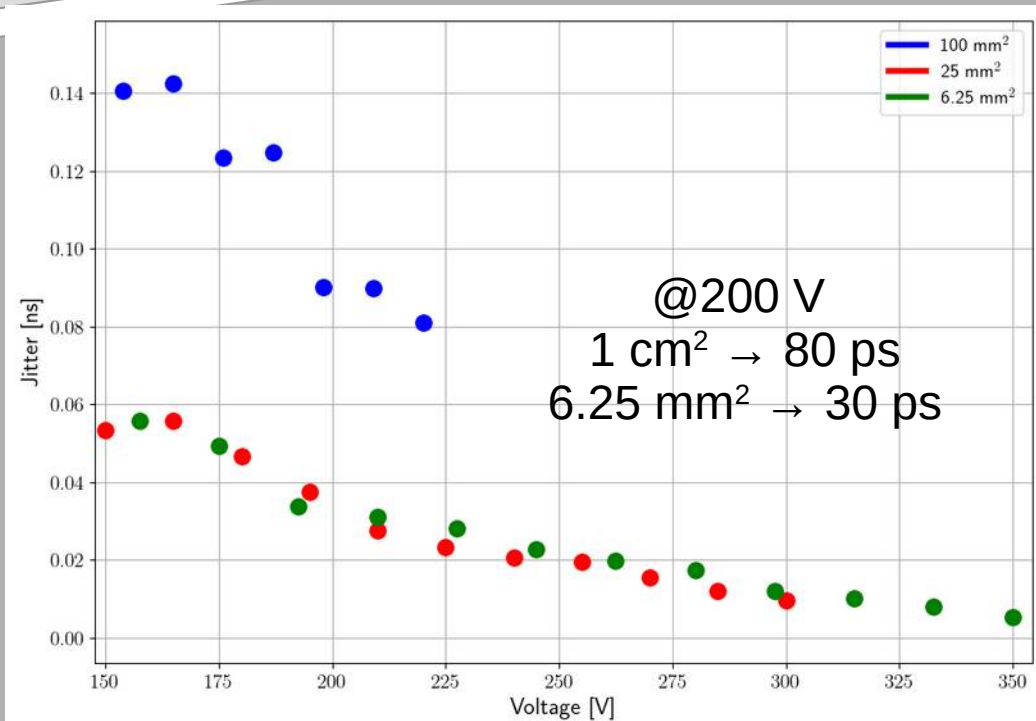
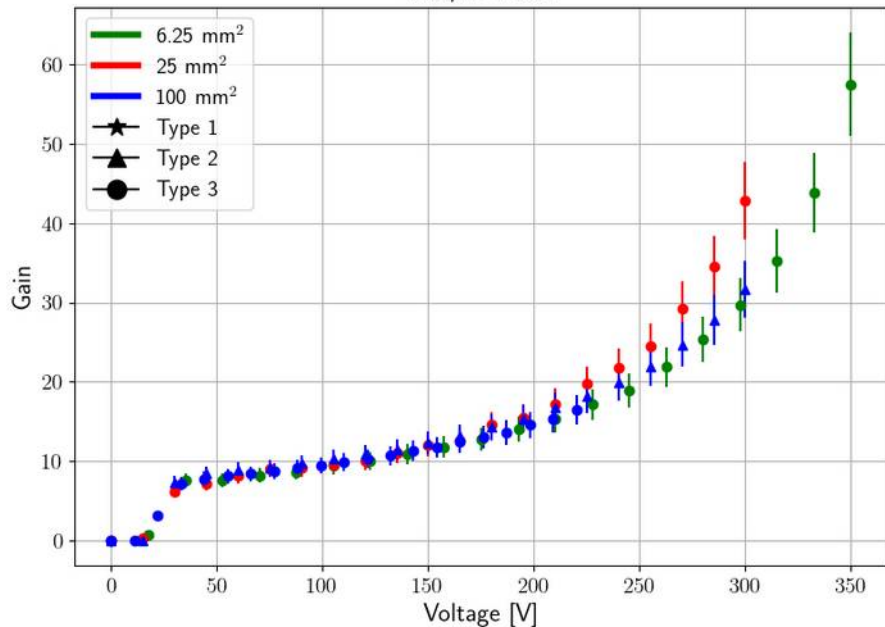
- ✓ Single Waveform → Noise Estimation
- ✓ Average Waveform → Slew Rate Estimation via Fitting the leading edge

$$\sigma_{Jitter} [ns] = \frac{N}{dV/dt} \propto \frac{T_{rise}}{SNR}$$



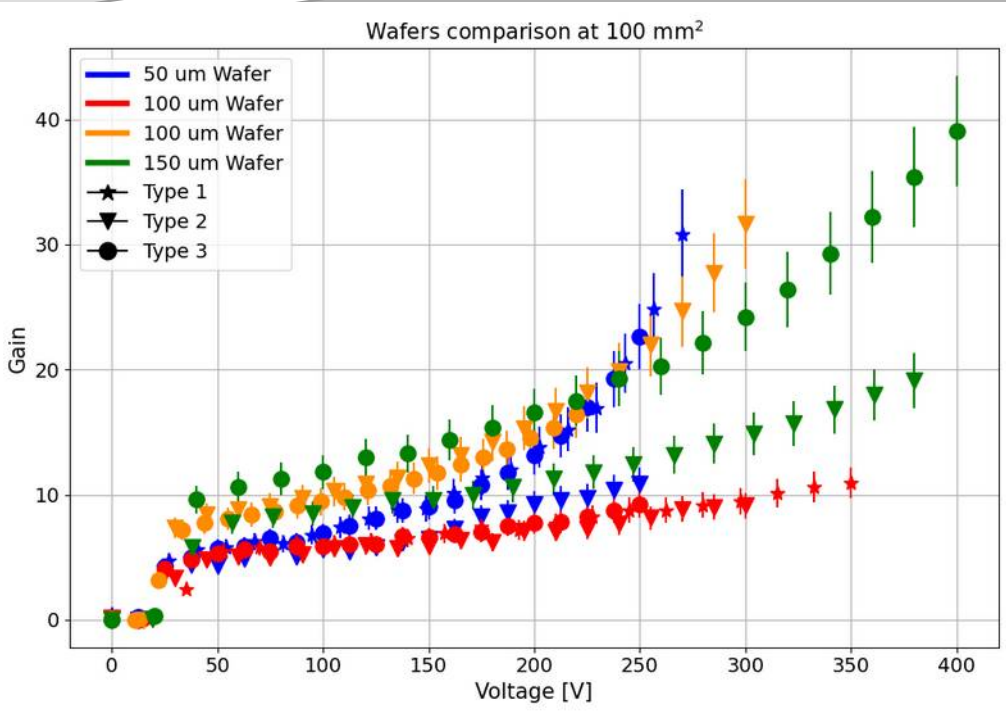
# LGADs Performance vs Area

100  $\mu\text{m}$  Wafer



**Sensitive area plays a major role in the jitter**

# 1 cm<sup>2</sup> LGADs Performance

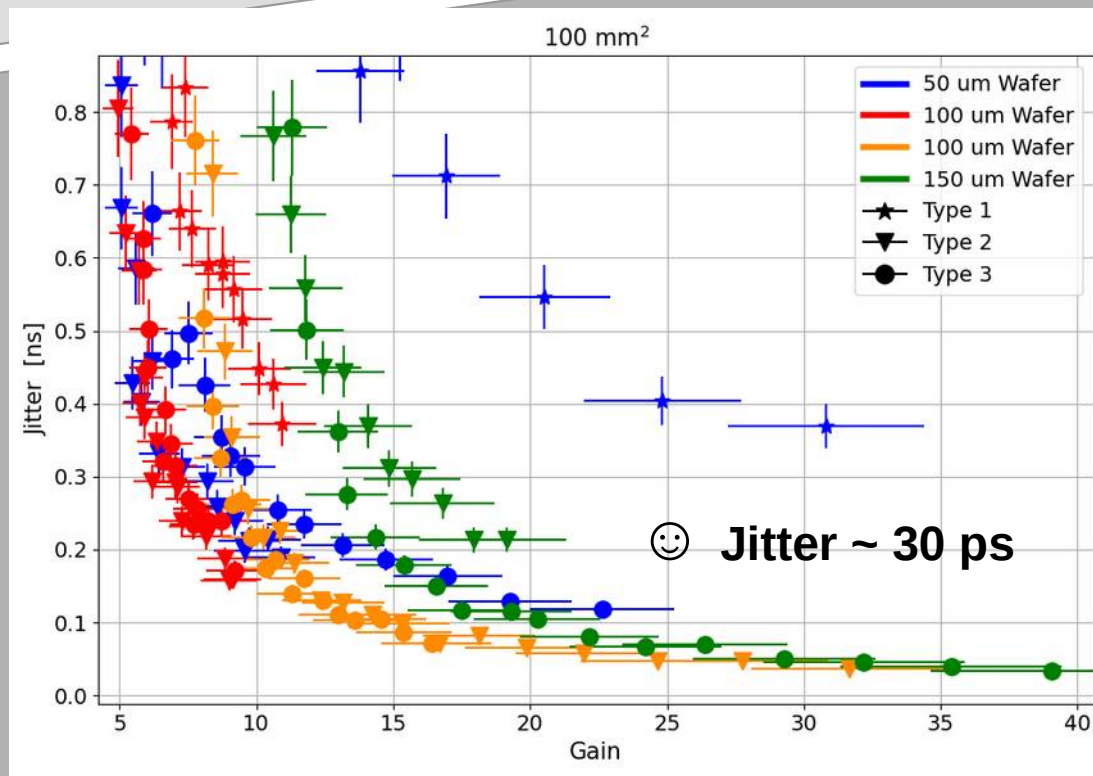


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Gain smaller than expected (100)

# 1 cm<sup>2</sup> LGADs Performance

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# 1 cm<sup>2</sup> LGADs Uniformity

1 cm = 30 ps  
@ light speed

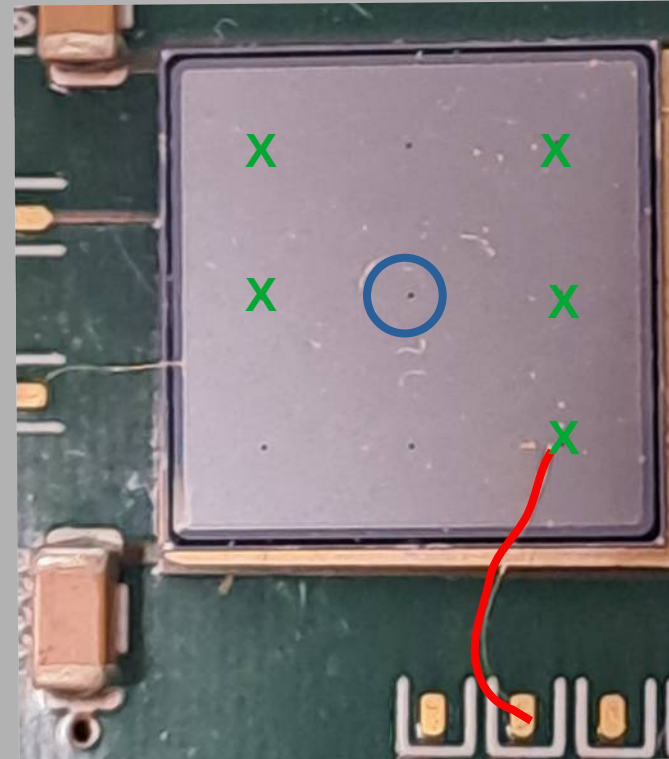


Signal formation and  
transmission variability

Reference point  
is the signal **bond**

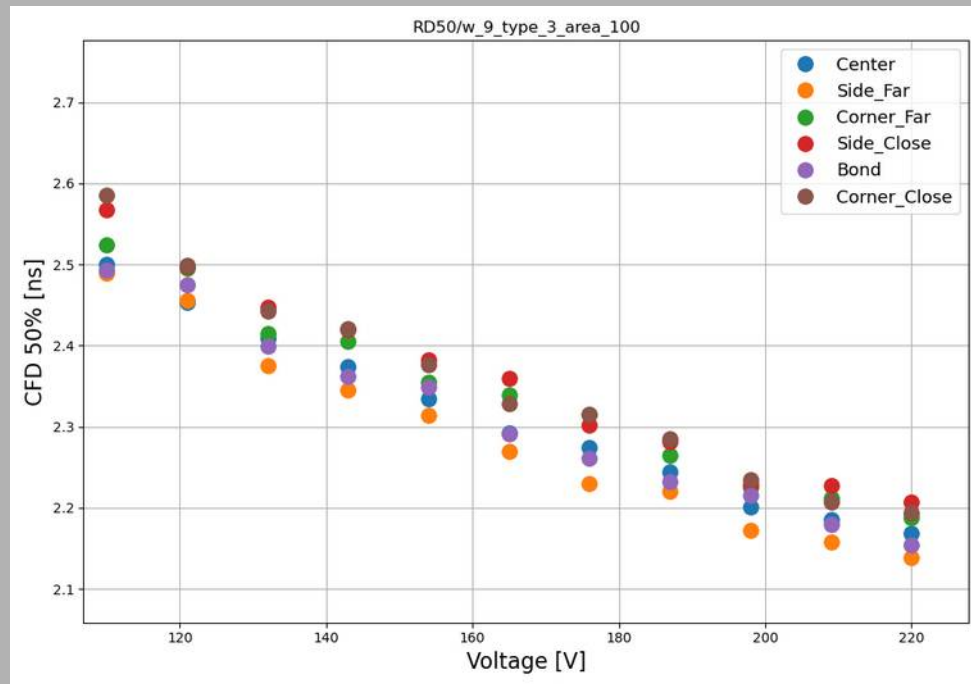
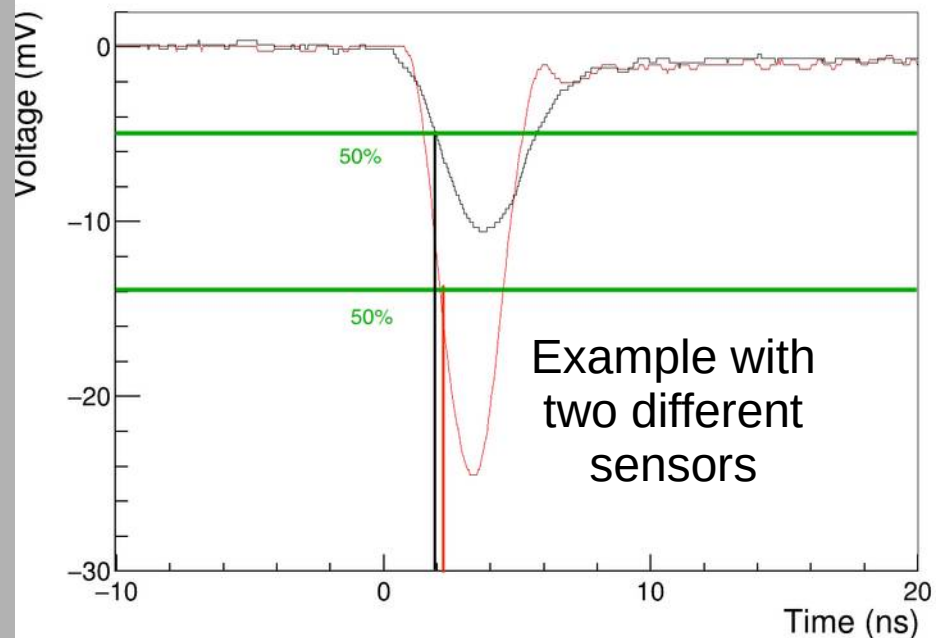
“Standard” Hit  
position

X = Uniformity  
Check points

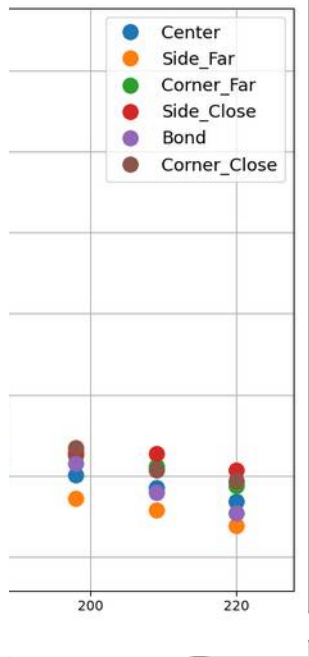
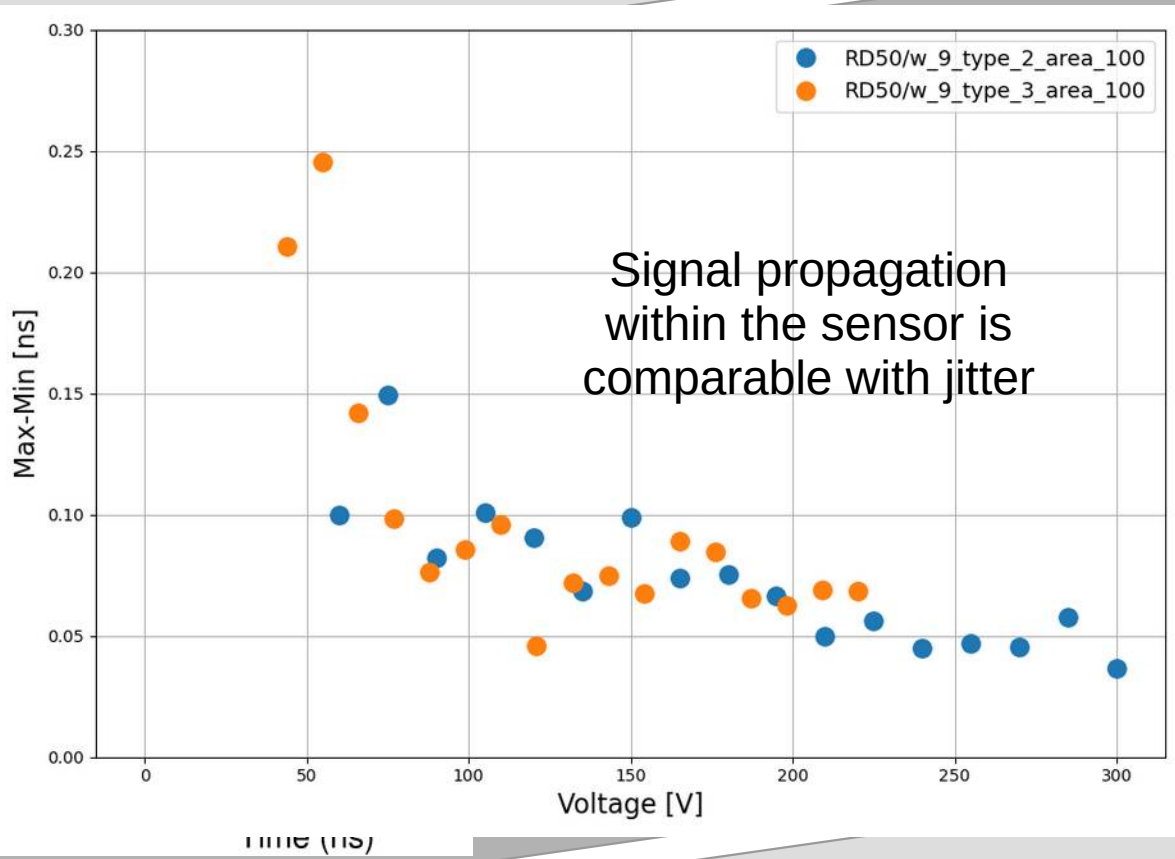
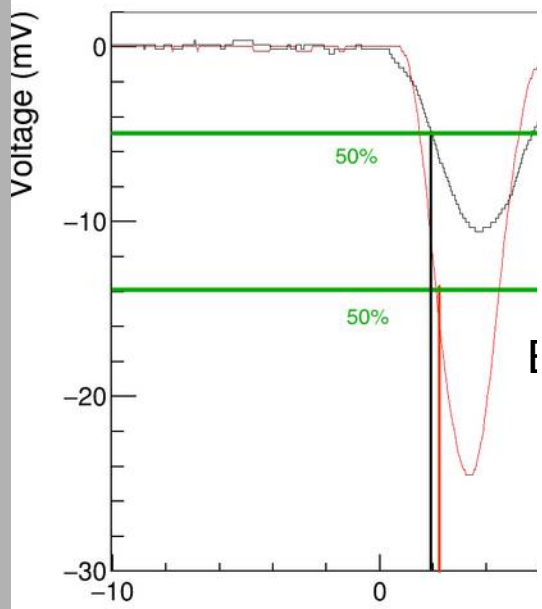




# 1 cm<sup>2</sup> LGADs Uniformity



# 1 cm<sup>2</sup> LGADs Uniformity



# Conclusions

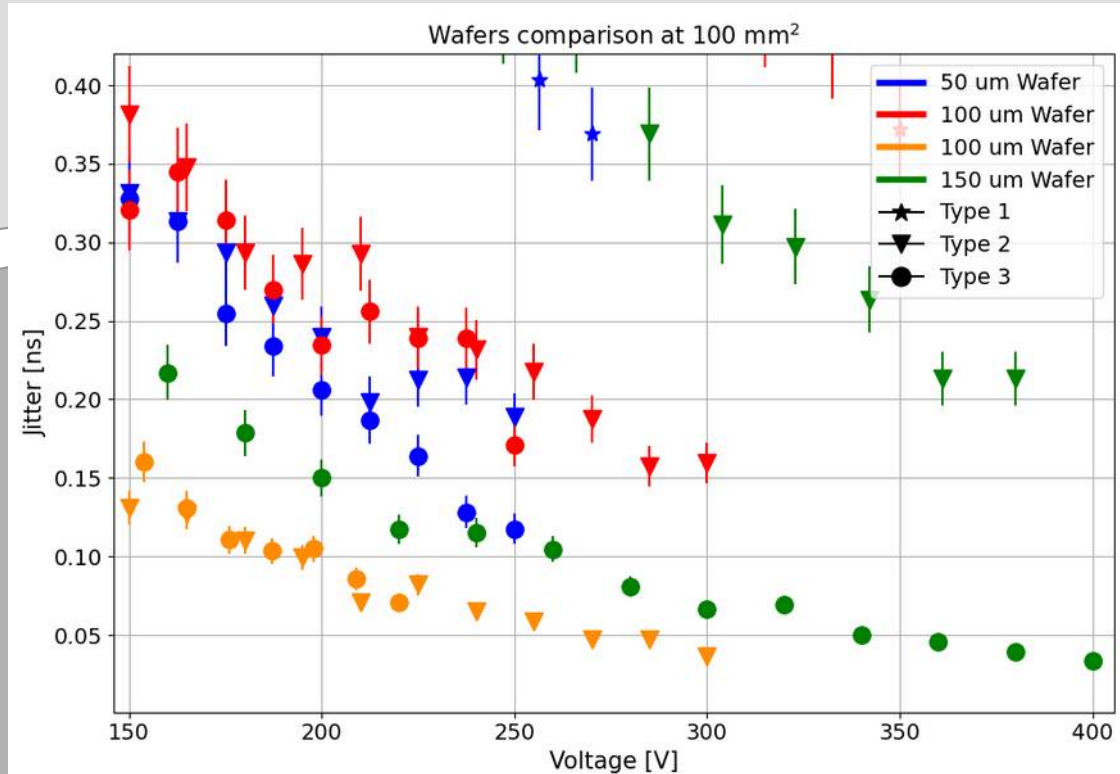
With the current technology, LGADs have time resolution capabilities  $O(10 \text{ ps})$ , in case of a  $\text{mm}^2$  device.

We produced  $1 \text{ cm}^2$  devices which achieve:

“

**100  $\mu\text{m}$  @ 300 V  $\rightarrow$  35 ps**  
**150  $\mu\text{m}$  @ 400 V  $\rightarrow$  30 ps**

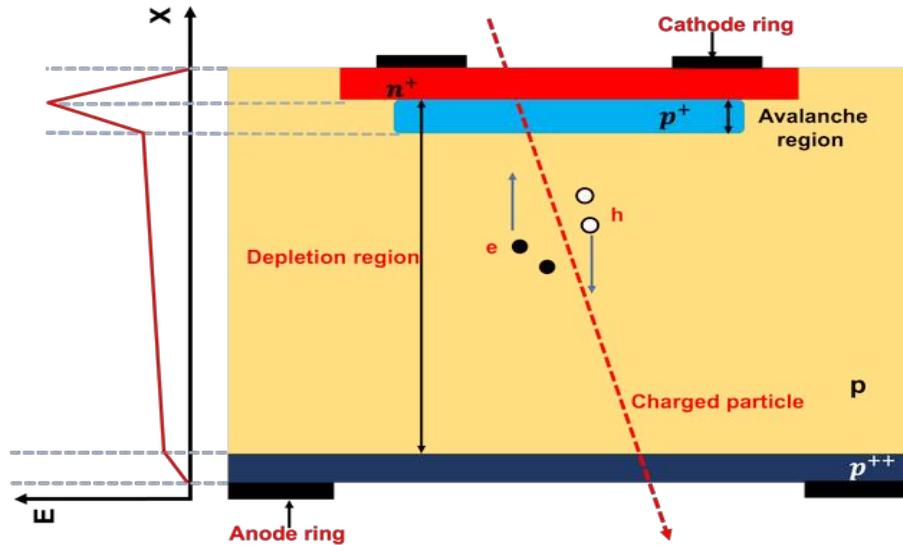
Must be considered the Time of Arrival ( $< 50 \text{ ps}$ ) of the signal for the Resolution, for every layout



”



# LGADs in Brief



[G. Kramberger et al. NIMA 2018,  
DOI: [https://doi.org/ 10.1016/j.nima.2018.02.018](https://doi.org/10.1016/j.nima.2018.02.018)]

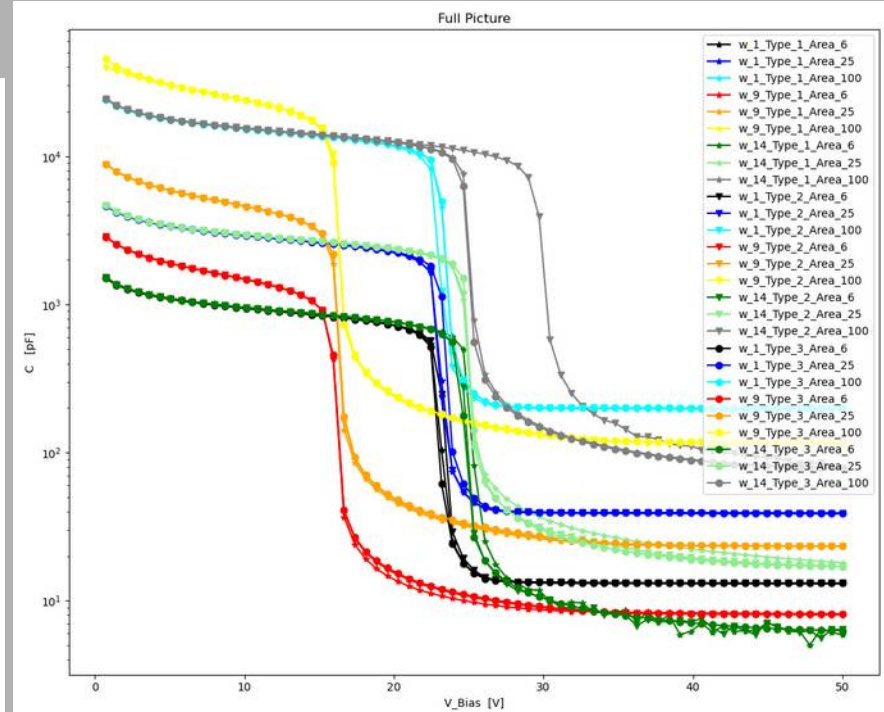
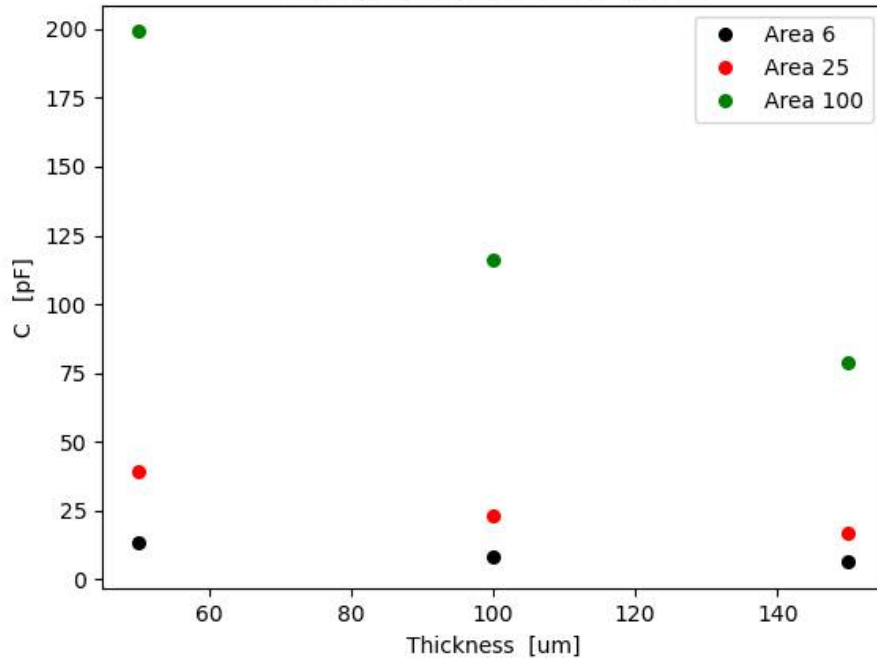
- Silicon detector with charge multiplication
- Gain layer provides high-field region
- Improved SNR: 5-10 times better than current PIN detectors
- Excellent radiation hardness  $> 10^{15}$  neq/cm<sup>2</sup>
- **Time resolution O(10 ps)**
- **Typical channel area 1-2 mm<sup>2</sup>**

$$i_S = -\frac{dQ}{dt} = q \vec{E}_w \vec{v}$$



# Preliminary: Capacitance

Thickness comparison of Type 3



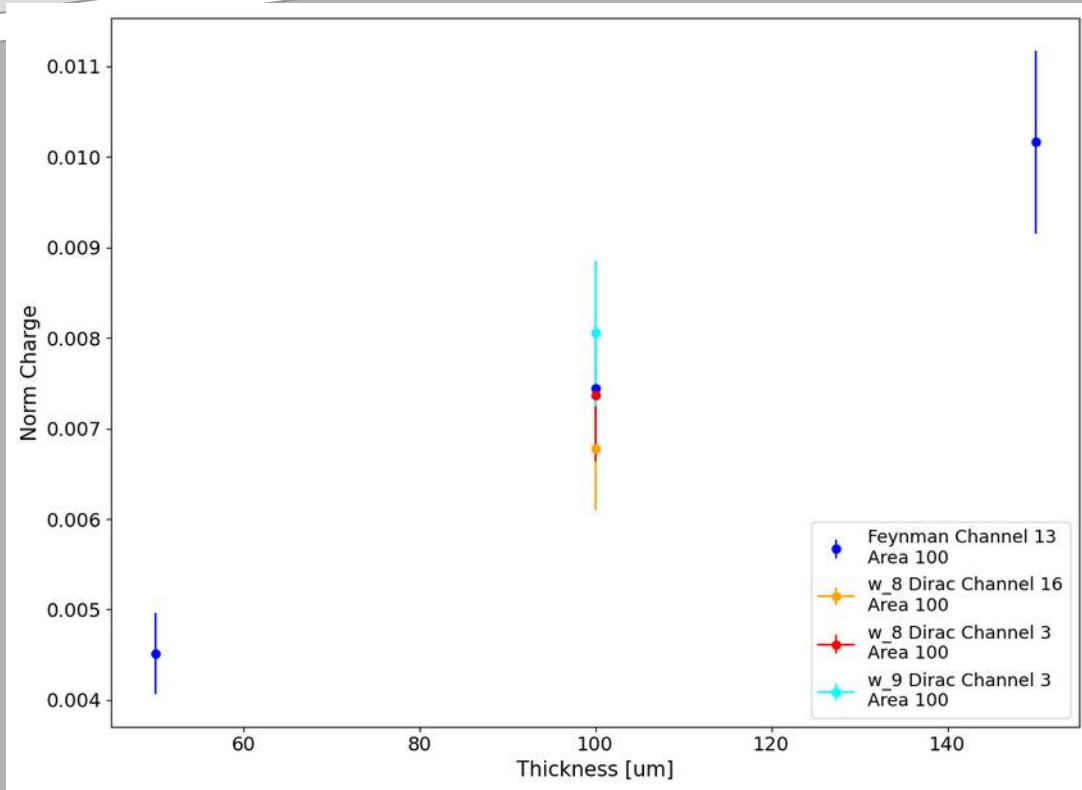
# Preliminary: Charge vs Thickness



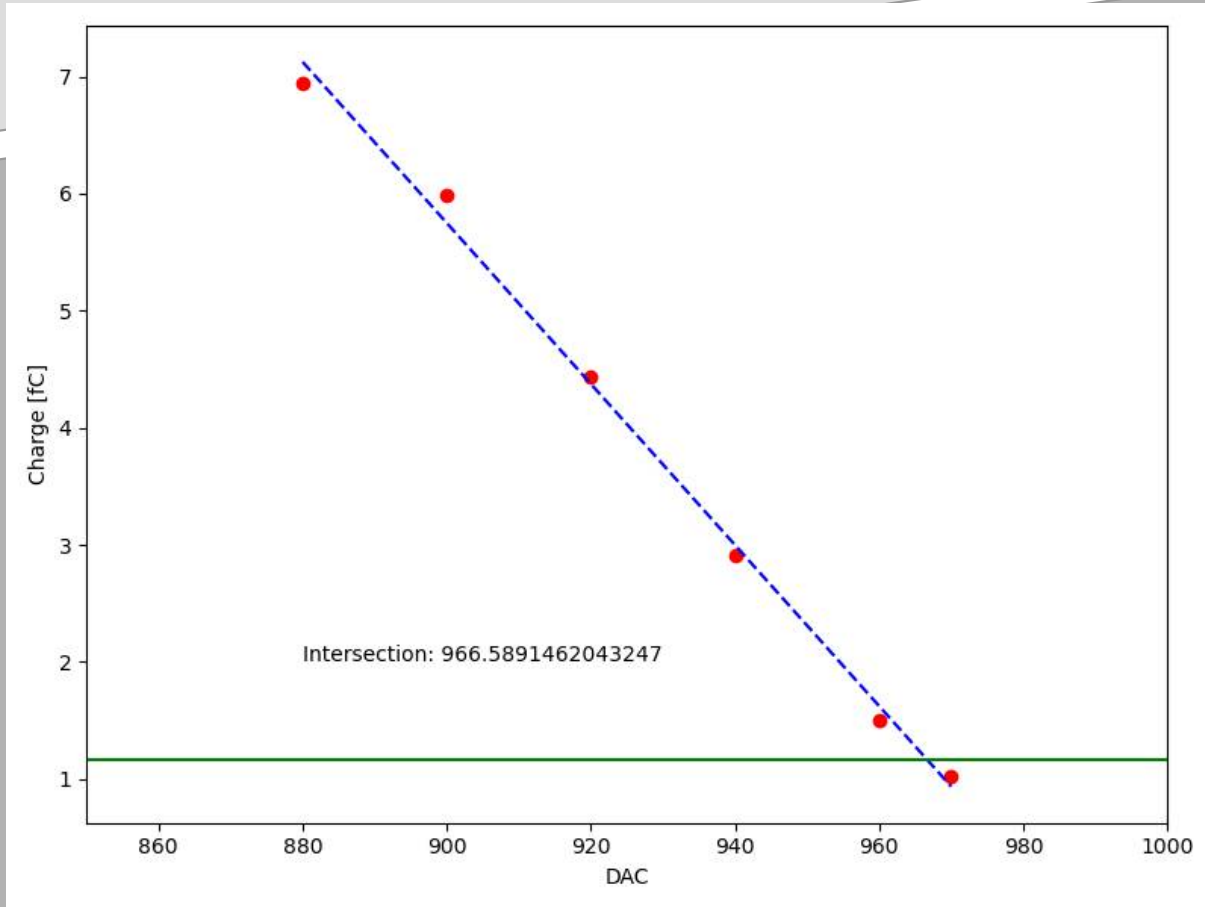
PCB channel Internal gain:

Beam Monitor Fluctuation  
→ Normalized Charge

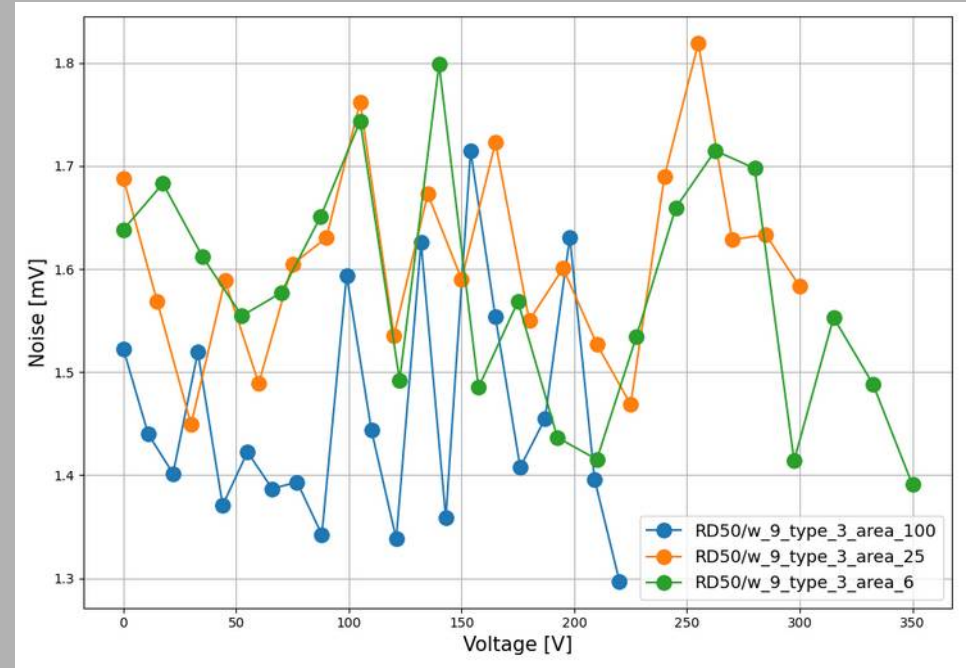
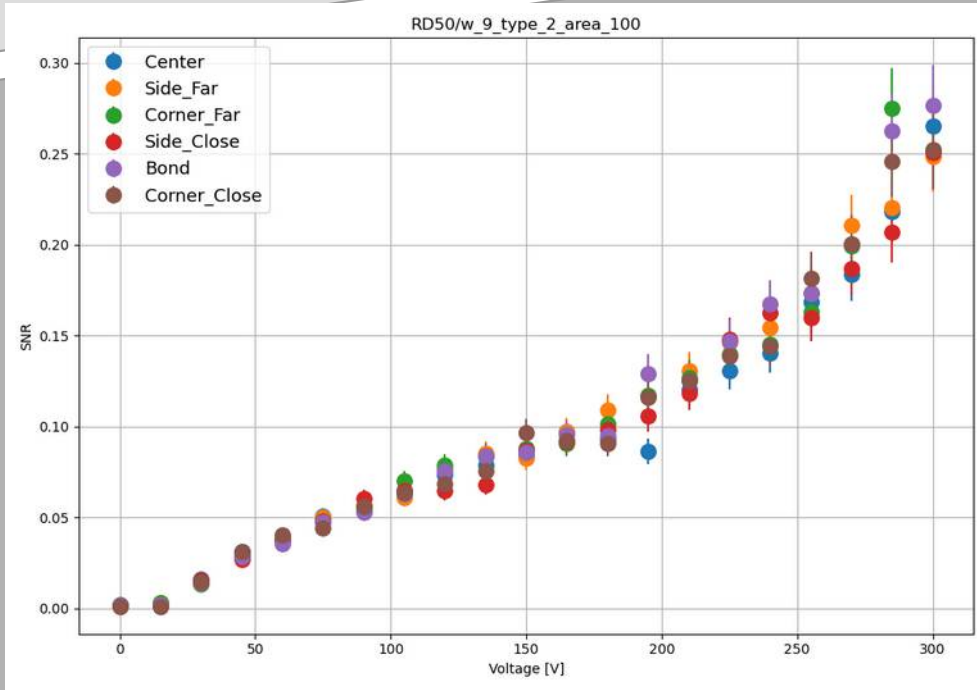
Charge Systematic Error  $\sim 8\%$



# Calibration

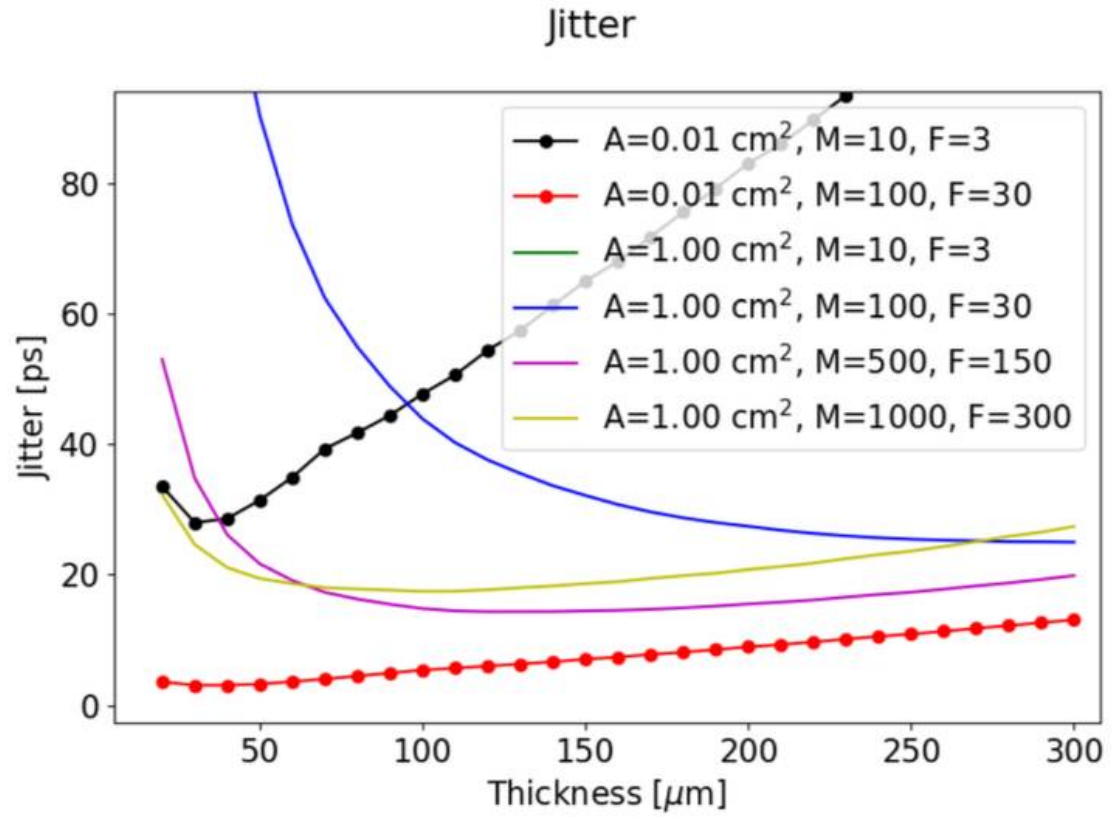


# Noise



# Jitter vs Thickness Simulations

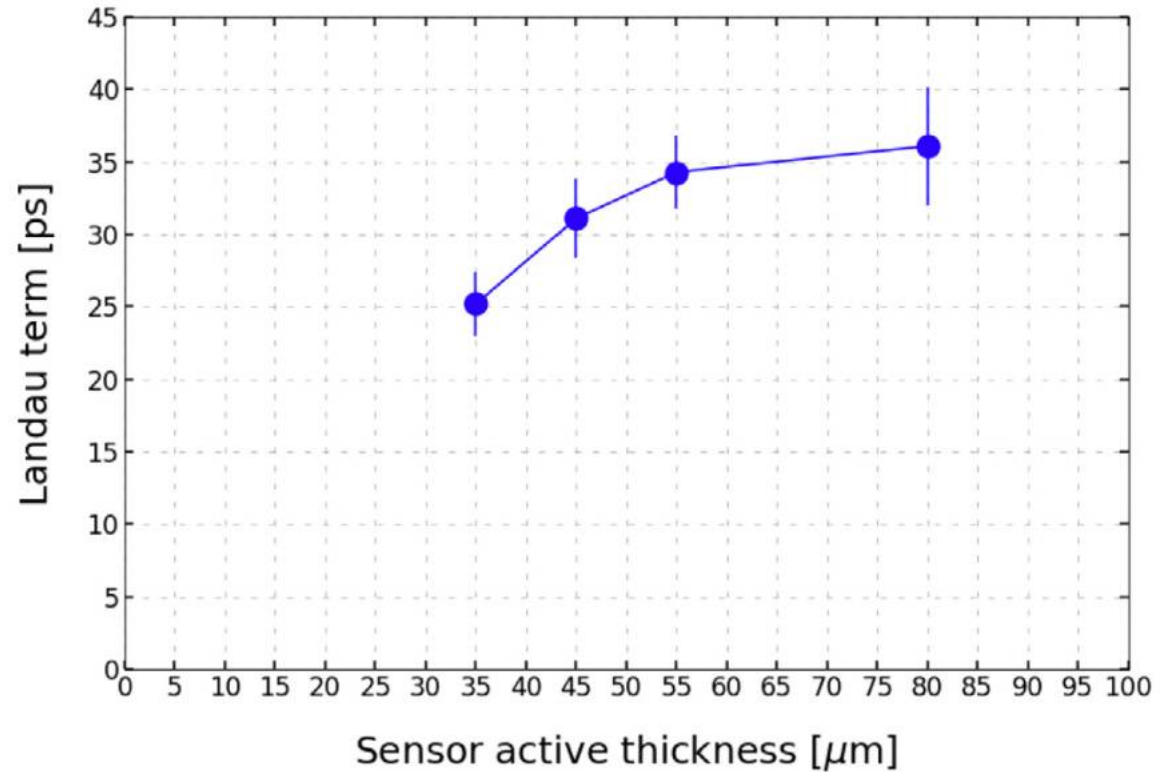
LT-Spice Simulation  
M = Gain  
F = Excess Noise  
Factor





# Landau Noise

The non-uniform energy deposition generated by an impinging MIP, amplified by the gain, creates variations of the signal shape on an event-to-event basis



# SLAPP Production

